

Title (en)

WAFER MARKING

Title (de)

WAFERMARKIERUNG

Title (fr)

MARQUAGE DE GALETTES

Publication

EP 1002338 A1 20000524 (DE)

Application

EP 98948693 A 19980730

Priority

- DE 9802187 W 19980730
- DE 19733410 A 19970801

Abstract (en)

[origin: DE19733410A1] A wafer marking is constituted by a plurality of soft marks produced in the surface of a wafer. These soft marks are at least 4 μm deep, have an inner diameter of at least 50 μm and in a particularly advantageous manner have a minimum rise at their surface of 0.2. These recesses (12) can be produced by means of a corresponding technology with depths of up to 6 μm .

IPC 1-7

H01L 23/544

IPC 8 full level

H01L 21/02 (2006.01); **H01L 23/544** (2006.01); **H01L 29/30** (2006.01)

CPC (source: EP KR US)

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DOCDB simple family (publication)

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